53124

RADIATION TOLERANT, ± 90V - 0.8A POWER MOSFET OPTOCOUPLER



| Features: | Applications: |
|---|---|
| Design Tested to 100 krad (Si) Total Dose Hermetically Sealed in 8-Pin Dual-In-Line Package Performance over -55°C to +125°C Compact Solid State Bi-directional Switch AC/DC Power Switching Maximum Average Current AC/DC: 0.8 A ⁽¹⁾ DC only: 1.6 A ⁽¹⁾ Per Derating Curves (Figure 3) AC/DC: 0.5 A DC only: 1.0 A Optically Coupled Input/Output Isolation Tested to 1500 VDC High Level of Transient Immunity 3 A Output Surge Current Shock and Vibration Resistant MIL-PRF-38534 Same foot print as HSSR7111 / Mii 53111 & Electrically Similar | Satellite/Space systems Military/High Reliability Systems Standard 28 VDC and 48 VDC Load Driver Standard 24 VAC Load Driver Aircraft Controls AC/DC Electromechanical and Solid State Relay Replacement I/O Modules Switching Heaters |

DESCRIPTION

The 53124 is a single channel power MOSFET optocoupler which is suitable as a pin for pin replacement for the Mii 53111 when radiation tolerant performance and similar electrical performance to the 53111 is required. The primary difference between the 53124 and 53111 is that the radiation tolerant power MOSFETs employed in the 53124 exhibit a higher $R_{DS(ON)}$. The higher values of $R_{DS(ON)}$ results in a lower current for the same power dissipation or higher power dissipation for the same current levels relative to the 53111.

The popular eight pin, hermetic dual-in-line ceramic package combined with 1500 VDC isolation between input and output, makes this optocoupler ideal for solid-state relay applications. Performance is specified over the full military temperature range. This device is available as COTS, or as fully compliant MIL-PRF-38534 Class H or with custom screening. Lead options support both through-hole and surface-mount assembly. Gold plated leads are standard, but other lead finishes per MIL-PRF-38534 are also available.

Functionally, the device operates as a single-pole, normally open (1 Form A) solid-state relay. The device is actuated by an input current, which can be supplied from standard logic types such as open-collector TTL. The input current biases a light emitting diode that is optically coupled to an integrated photovoltaic diode array. The photovoltaic array powers control circuitry that operates the output MOSFETs. Optimum switching of either AC or DC loads is provided by a configurable output. For AC loads, Connection A in Figure 1 must be used. Connection A will also switch DC loads but Connection B, in Figure 1, provides DC-only operation with the advantages of substantial reduction in on-resistance and twice the output current capability as that obtained with Connection A.

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ABSOLUTE MAXIMUM RATINGS:

| Storage Temperature Range Operating Ambient Temperature - T_A Junction Temperature - T_J Operating Case Temperature - T_c Lead Solder Temperature for 10 seconds | 55°C to +125°C +150°C +145°C ⁽²⁾ |
|--|---|
| | (1.6 mm below seating plane) |
| Average Input Current - I _F | · · · · · · · · · · · · · · · · · · · |
| Peak Repetitive Input Current - I _{Fpk} | 40 mA |
| | (Pulse width < 100 ms; duty cycle < 50%) |
| Peak Surge Input Current - I _{Fpk} surge | |
| | (Pulse width < 0.2 ms; duty cycle < 0.1%) |
| Reverse Input Voltage - V _R | 5 V |
| Average Output Current | (1) |
| Connection A - I _o | |
| Connection B - I _o | 1.6 A (1) |
| Average Output Current, derated per Figure 3 | |
| Connection A - I _o | |
| Connection B - I ₀ | 1.0 A |
| Single Shot Output Current - Figure 4 | 2 Λ |
| Connection A - I _{Opk} surge (Pulse width < 10 ms) Connection B - I _{Opk} surge (Pulse width < 10 ms) | |
| Output Voltage | UA |
| Connection A - V_0 | –90 V to +90 V |
| Connection B - V_0 | |
| Average Output Power Dissipation - Figure 5 | |
| U 1 U | |

RECOMMENDED OPERATING CONDITIONS:

| Parameter | Symbol | Min. | Max. | Units |
|--------------------------|---------------------|------|------|-------|
| Input Current (ON) | I _{F (ON)} | 5 | 20 | mA |
| Input Voltage (OFF) | $V_{F(OFF)}$ | 0 | 0.6 | VDC |
| Operating Temperature | T _A | -55 | +125 | °C |

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ELECTRICAL SPECIFICATIONS (Pre-Irradiation)

 T_A = -55°C to +125°C, unless otherwise specified.

| Parameter | Symbol | Min. | Тур.* | Max. | Unit s | Test Conditions | Notes |
|--|-----------------------|------|------------------|------|-----------|---|-------------|
| Output Withstand Voltage | V _{O(OFF)} | 90 | 110 | | v | V _F = 0.6 V I _O = 10 μA | |
| Output On-Resistance (Connection A) | _ | | 0.8 | 2.5 | Ω | I_F = 10 mA I_O = 500 mA (pulse duration ≤ 30 ms) | _4, |
| Output On-Resistance (Connection B) | R _(ON) | | 0.2 | 0.7 | Ω | $\label{eq:IF} \begin{array}{l} I_{\text{F}} = 10 \text{ mA} \\ I_{\text{O}} = 1 \text{ A} \\ (\text{pulse duration} \leq 30 \text{ ms}) \end{array}$ | Figure 1 |
| Output Leakage Current | I _{O (OFF)} | | 10 ⁻⁴ | 10 | μA | V _F = 0.6 V V _O = 90 V | |
| Input Forward Voltage | V _F | 1.0 | 1.24 | 1.7 | V | I _F = 10 mA | |
| Input Reverse Breakdown Voltage | V _R | 5 | | | V | I _F = 10 μA | |
| Input-Output Insulation | I _{I-O} | | | 1 | μA | RH \leq 45%, t = 5 s V _{I-O} = 1500 VDC T _A = 25°C | 5, 6 |
| Turn-On Time | t _{on} | | 1.25 | 6 | ms | I _F = 10 mA V _{DD} = 28 V I _O = 800 mA | Figure 6 |
| Turn-Off time | t _{OFF} | | | 0.25 | ms | I _F = 10 mA V _{DD} = 28 V I _O = 800 mA | Figure 6 |
| Output Transient Rejection | dV _o dt | 1000 | | | V/µs | $V_{\text{PEAK}} = 50 \text{ V}$ $C_{\text{M}} = 1000 \text{ pF}$ $C_{\text{L}} = 15 \text{ pF}$ $R_{\text{M}} \ge 1 \text{ M}\Omega$ | Figure 7 |
| Input-Output Transient Rejection | $\frac{dV_{I-O}}{dt}$ | 500 | | | V/µs | $V_{DD} = 5 V$ $V_{I-0 (PEAK)} = 50 V$ $R_L = 20 k\Omega$ $C_L = 15 pF$ | Figure 8 |

* All typical values are at T_A = 25°C, I_{F (ON)} = 10 mA, V_{F (OFF)} = 0.6 V unless otherwise specified.

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TYPICAL CHARACTERISTICS - (Pre-Irradiation)

All typical values are at $T_A = 25^{\circ}$ C, $I_{F(ON)} = 10$ mA, $V_{F(OFF)} = 0.6$ V unless otherwise specified.

| Parameter | Symbol | Test Conditions | Typical Value | Units | Notes |
|-------------------------------------|-------------------------------|---|------------------|-------|-------|
| Output Off-Capacitance | $C_{O (OFF)}$ | V ₀ = 28 V f = 1 MHz | 145 | pF | |
| Output Offset Voltage | V _{os} | I _F = 10 mA I _O = 0 mA | 2 | μV | 7 |
| Input Diode Temperature Coefficient | $\Delta V_{F} / \Delta T_{A}$ | I _F = 10 mA | -1.4 | mV/°C | |
| Input Capacitance | C _{IN} | V _F = 0 V f = 1 MHz | 20 | pF | 8 |
| Input-Output Capacitance | C _{I-O} | V _{I-O} = 0 V f = 1 MHz | 1.5 | pF | 5 |
| Input-Output Resistance | R _{I-O} | V _{I-O} = 500 V t = 60 s | 10 ¹³ | Ω | 5 |

Notes:

- 1. Maximum average current rating where the case temperature (T_c) is maintained below 120°C.
- 2. Maximum junction to case thermal resistance for the device is 15°C/W, where case temperature (T_c) is measured at the center of the package bottom.
- 3. For rating, see Figure 5. The output power P_D rating curve is obtained when the part is handling the maximum average output current I_0 as shown in Figure 3.
- 4. During the pulsed R_{ON} measurement (I_O duration < 30 ms), ambient (T_A) and case temperature (T_C) are equal.
- 5. Pins 2 through 3 shorted together and pins 5 through 8 shorted together.
- 6. This is a momentary withstand test, not an operating condition.
- 7. V_{OS} is a function of I_F and is defined between pins 5 and 8, with pin 5 as the reference. V_{OS} must be measured in a stable ambient (free of temperature gradients).
- 8. Zero-bias capacitance measured between the LED anode and cathode.

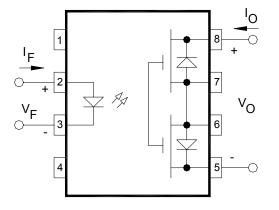
CAUTION:

Care should be taken not to exceed the maximum output power dissipation, maximum case temperature, and maximum junction temperature when repetitively switching loads.

| Case outlines | A, B, and C | | |
|-----------------|---------------------------------|------------------------------------|--|
| Terminal number | Terminal symbol | | |
| | Connection A (AC or DC load) | Conneciton B (DC load only) | |
| 1 | NC | NC | |
| 2 | V _{F+} | V _{F+} | |
| 3 | V _{F-} | V _{F-} | |
| 4 | NC | NC | |
| 5 | V _{O-} | V _{O+} | |
| 6 | NC | NC | |
| 7 | NC | N _{O-} | |
| 8 | V _{O+} | N _{O-} V _{O+} | |

NC = No connection

CONNECTION A AC/DC CONNECTION



CONNECTION B DC CONNECTION

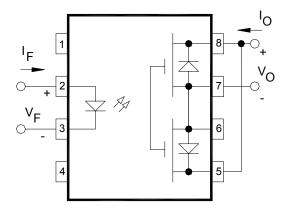
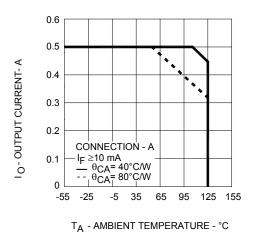


Figure 1 - Terminal Connections

| INPUT | OUTPUT |
|-------|--------|
| OFF | OFF |
| ON | ON |

Figure 2 - Truth Table



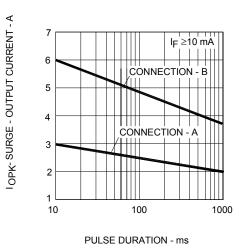
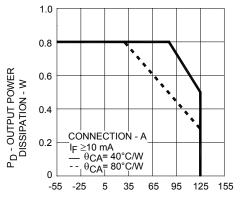


Figure 3. Maximum Average Output Current Rating vs. Ambient Temperature.

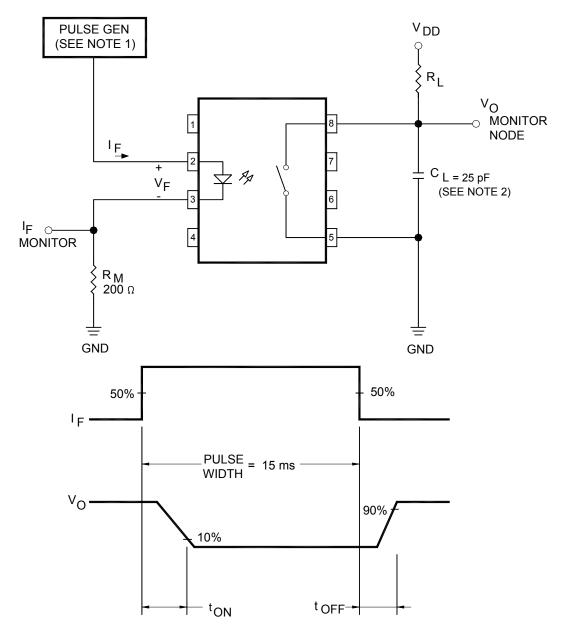
Figure 4. Single Shot (nonrepetitive) Output Current vs. Pulse Duration.



T_A - AMBIENT TEMPERATURE - °C

Figure 5. Output Power Rating vs. Ambient Temperature.

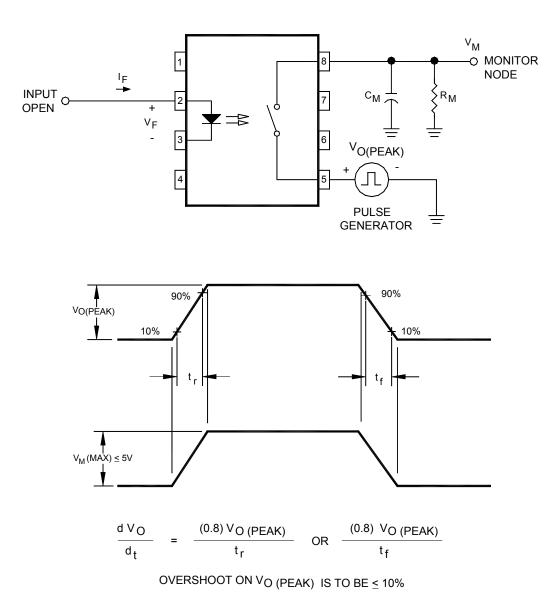
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NOTES:

- 1. PULSE GENERATOR HAS THE FOLLOWING CHARACTERISTICS: OUTPUT IMPEDANCE = 50 Ω AND t_r = t_f = 5.0 ns.
- 2. LOAD CAPACITANCE (C1) INCLUDES PROBE AND JIG CAPACITANCE.

Figure 6. Switching Test Circuit and Waveform.

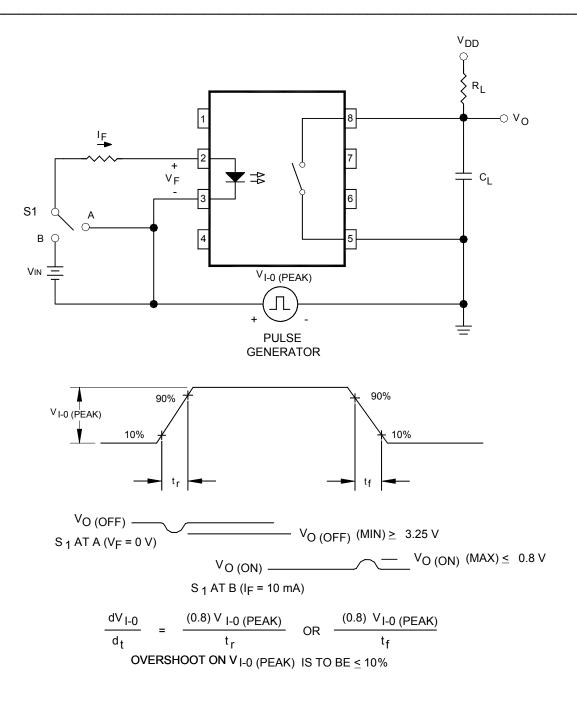


NOTES:

- 1. C_M INCLUDES PROBE AND FIXTURE CAPACITANCE. 2. R_M INCLUDES PROBE AND FIXTURE RESISTANCE.

Figure 7. Output Transient Rejection Test Circuit and Waveform.

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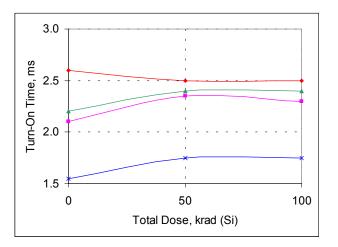
NOTES:

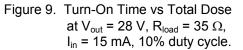
1. LOAD CAPACITANCE (C1) INCLUDES PROBE AND FIXTURE CAPACITANCE.

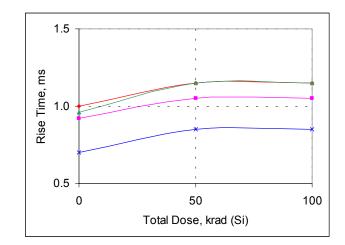
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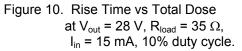
TOTAL DOSE TEST RESULTS

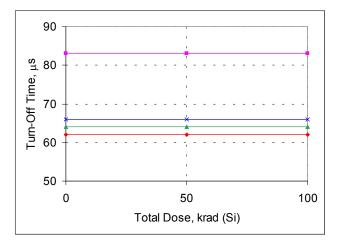
<u>Disclaimer</u>: The data of 4 representative units irradiated in Cobalt-60 chamber is only typical of one lot of solid state relays. Micropac does not guarantee performance of its SSR to these radiation levels. Individual lots have to be screened to guarantee the performance.

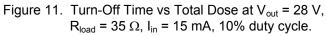












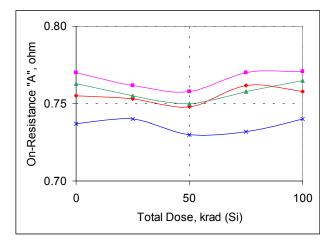


Figure 12. On-Resistance "A" vs Total Dose at I_F =10 mA, I_{out} = 40 mA for 1second.

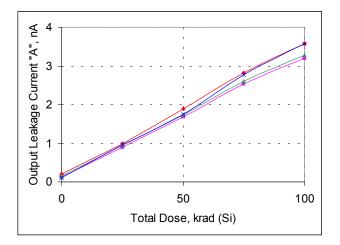


Figure 14. Output Leakage Current "A" vs Total Dose at V_F = 1.0 V, V_{out} = 90 V.

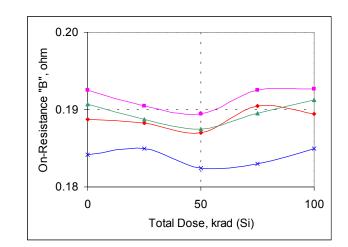


Figure 13. On-Resistance "B" vs Total Dose at I_F =10 mA, I_{out} = 40 mA for 1second.

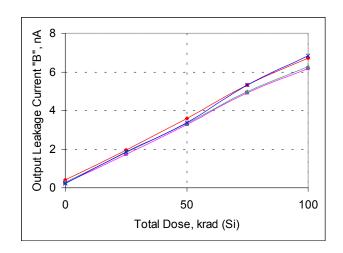


Figure 15. Output Leakage Current "B" vs Total Dose at V_F = 1.0 V, V_{out} = 90 V.

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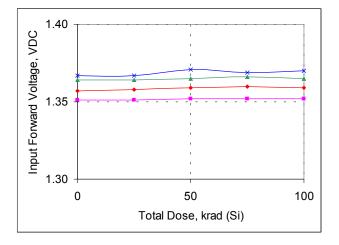


Figure 16. Input Forward Voltage vs Total Dose at I_F =15 mA.

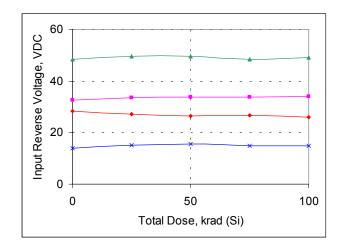
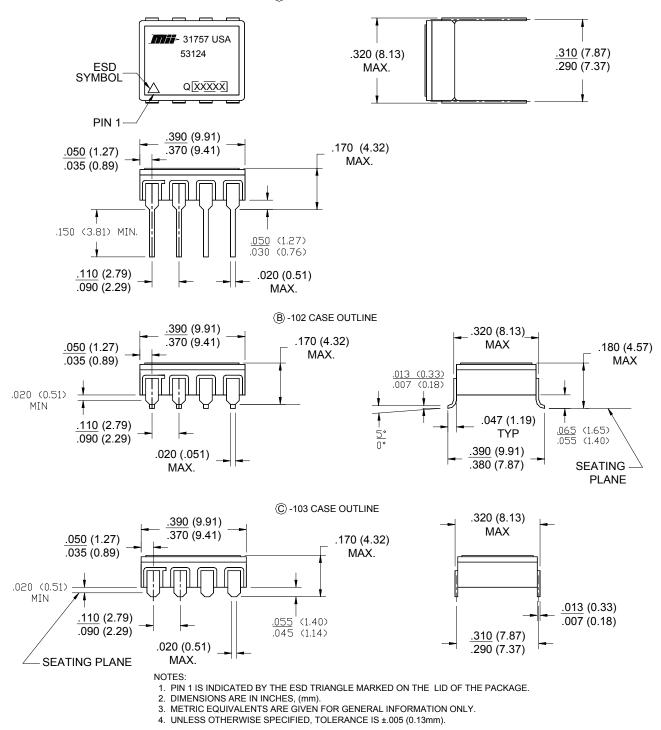


Figure 17. Input Reverse Voltage vs Total Dose at I_R = 10 μ A.

Case Outlines





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